

GENERAL DESCRIPTION

The SGM8049-1 (single), SGM8049-2 (dual) and SGM8049-4 (quad) are micro-power and low voltage operational amplifiers, which are suitable for battery-powered systems. These devices can operate from 1.8V to 5.5V single supply or from $\pm 0.9V$ to $\pm 2.75V$ dual power supplies, and consume only 2.5 μA quiescent current per amplifier. They also provide rail-to-rail input and output operation.

The SGM8049-1/2/4 provide low power, low bias current and low noise. These devices fit in small packages. The combination of the above features makes them appropriate for various applications.

The SGM8049-1 is available in Green SC70-5, SOT-23-5 and TDFN-2 \times 2-6L packages. The SGM8049-2 is available in Green SOT-23-8 and SOIC-8 packages. The SGM8049-4 is available in a Green TSSOP-14 package. They are specified over the extended $-40^{\circ}C$ to $+125^{\circ}C$ temperature range.

FEATURES

- **Support Single or Dual Power Supplies:**
1.8V to 5.5V or $\pm 0.9V$ to $\pm 2.75V$
- **Low Quiescent Current:** 2.5 μA /Amplifier (TYP)
- **Low Offset Voltage:** 0.85mV (MAX)
- **Low 0.1Hz to 10Hz Noise:** 3.5 μV_{P-P}
- **CMRR:** 100dB (TYP)
- **PSRR:** 2.5 $\mu V/V$ (TYP)
- **Open-Loop Voltage Gain:** 118dB (TYP)
- **$-40^{\circ}C$ to $+125^{\circ}C$ Operating Temperature Range**
- **Small Packaging:**
SGM8049-1 Available in Green SC70-5, SOT-23-5 and TDFN-2 \times 2-6L Packages
SGM8049-2 Available in Green SOT-23-8 and SOIC-8 Packages
SGM8049-4 Available in a Green TSSOP-14 Package

APPLICATIONS

- Battery-Powered Instrumentation
- Wearable Equipment
- Portable Equipment
- Handheld Test Equipment
- Medical Instrumentation

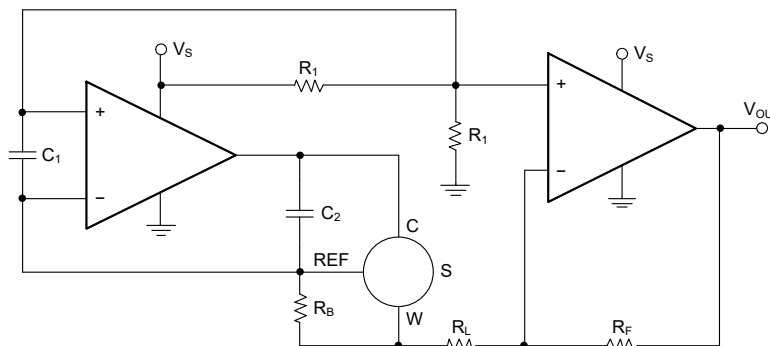


Figure 1. SGM8049-1 in Portable Gas Meter Application

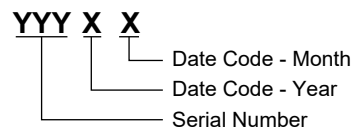
PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM8049-1	SOT-23-5	-40°C to +125°C	SGM8049-1XN5G/TR	SVAXX	Tape and Reel, 3000
	SC70-5	-40°C to +125°C	SGM8049-1AXC5G/TR	SZAXX	Tape and Reel, 3000
	SC70-5	-40°C to +125°C	SGM8049-1BXC5G/TR	SUEXX	Tape and Reel, 3000
	TDFN-2x2-6L	-40°C to +125°C	SGM8049-1XTDI6G/TR	SZC XXXX	Tape and Reel, 3000
SGM8049-2	SOT-23-8	-40°C to +125°C	SGM8049-2XN8G/TR	SVBXX	Tape and Reel, 3000
	SOIC-8	-40°C to +125°C	SGM8049-2XS8G/TR	SGM 80492XS8 XXXXX	Tape and Reel, 2500
SGM8049-4	TSSOP-14	-40°C to +125°C	SGM8049-4XTS14G/TR	SGM80494 XTS14 XXXXX	Tape and Reel, 4000

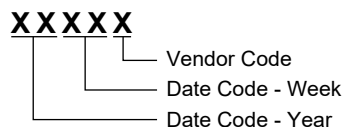
MARKING INFORMATION

NOTE: XX = Date Code. XXXX = Date Code. XXXXX = Date Code and Vendor Code.

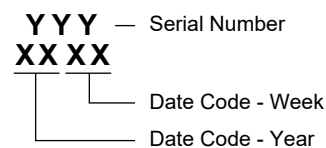
SOT-23-5/SC70-5/SOT-23-8



SOIC-8/TSSOP-14



TDFN-2x2-6L



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, +V _S to -V _S	6V
Signal Input Voltage Terminals (-V _S) - 0.3V to (+V _S) + 0.3V	
Signal Input Current Terminals	±10mA
Output Short-Circuit Current	30mA
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 10s)	+260°C
ESD Susceptibility	
HBM	6000V
MM	400V
CDM	1000V

RECOMMENDED OPERATING CONDITIONS

Input Voltage Range	1.8V to 5.5V
Operating Temperature Range	-40°C to +125°C

OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

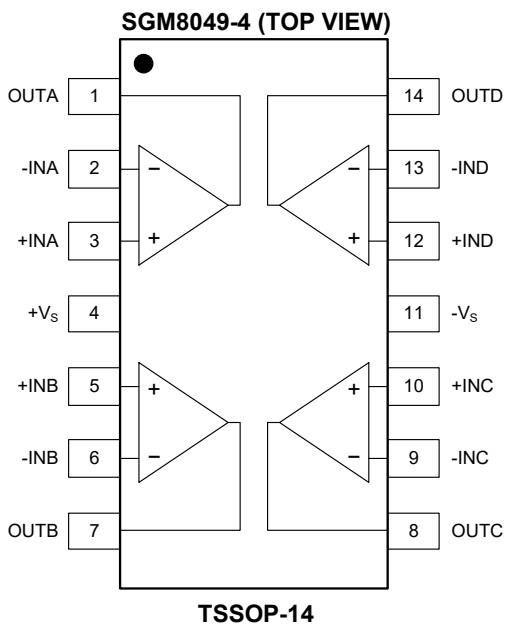
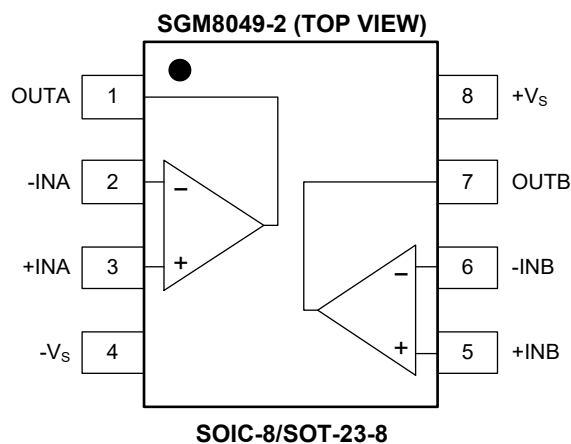
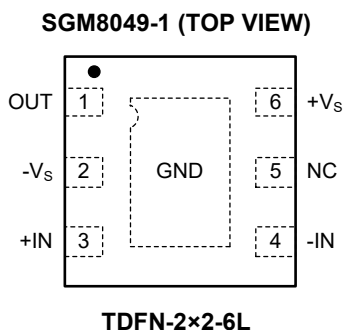
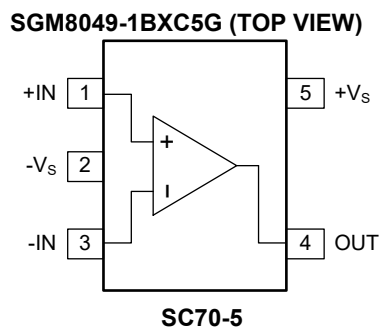
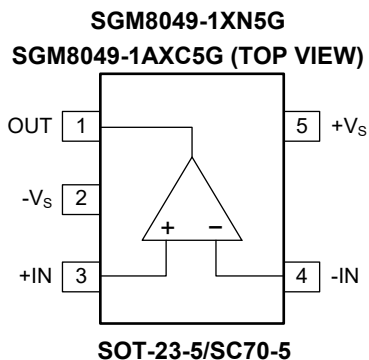
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

PIN CONFIGURATIONS



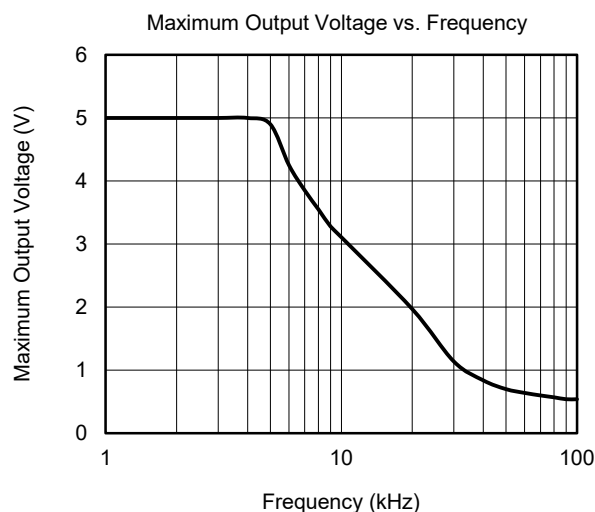
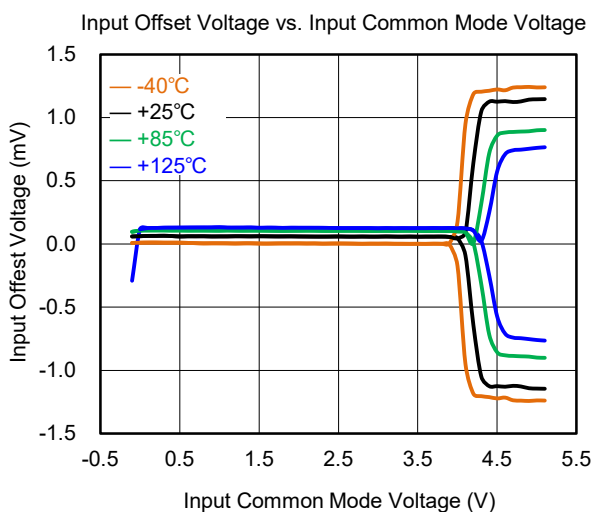
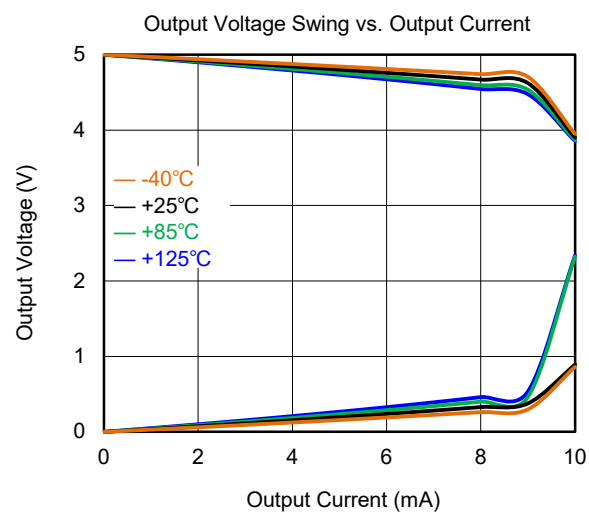
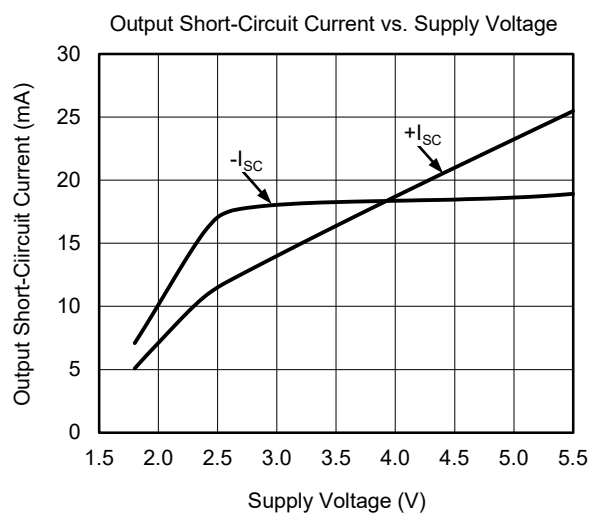
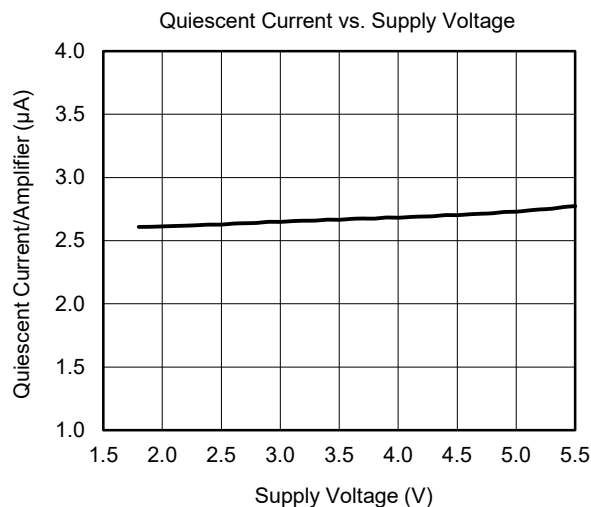
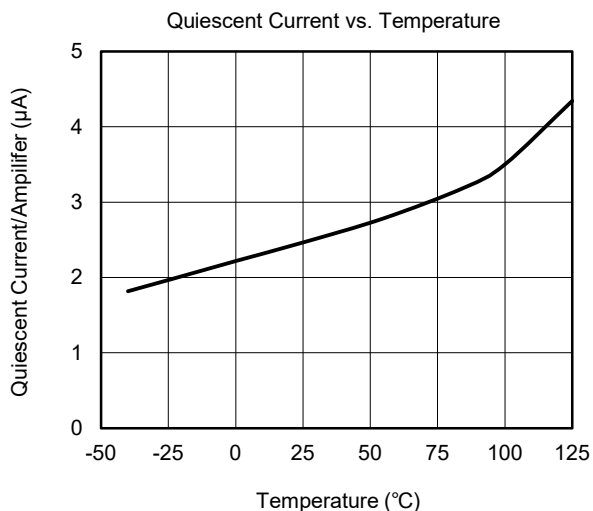
ELECTRICAL CHARACTERISTICS

($V_S = 1.8V$ to $5.5V$, $V_{CM} < (+V_S) - 1.2V$, and $R_L = 25k\Omega$ connected to $V_S/2$, typical values are at $T_A = +25^\circ C$, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input Characteristics						
Input Offset Voltage	V_{OS}	$V_S = 5V$		0.2	0.85	mV
		$-40^\circ C \leq T_A \leq +125^\circ C$			1	
Input Bias Current	I_B	$V_S = 5V, V_{CM} \leq V_S/2$		± 1		pA
Input Offset Current	I_{OS}	$V_S = 5V$		± 1		pA
Input Common Mode Voltage Range	V_{CM}		$(-V_S) - 0.1$		$(+V_S) + 0.1$	V
Common Mode Rejection Ratio	CMRR	$-V_S < V_{CM} < (+V_S) - 1.2V$	81	100		dB
		$-40^\circ C \leq T_A \leq +85^\circ C$	80			
		$-40^\circ C \leq T_A \leq +125^\circ C$	75			
Open-Loop Voltage Gain	A_{OL}	$V_S = 5V, R_L = 25k\Omega,$ $100mV < V_{OUT} < (+V_S) - 100mV$	100	118		dB
		$-40^\circ C \leq T_A \leq +125^\circ C$	98			
		$V_S = 5V, R_L = 5k\Omega,$ $500mV < V_{OUT} < (+V_S) - 500mV$	100	116		
		$-40^\circ C \leq T_A \leq +125^\circ C$	98			
Input Offset Voltage Drift	$\Delta V_{OS}/\Delta T$	$-40^\circ C \leq T_A \leq +85^\circ C$		0.5		$\mu V/^\circ C$
		$-40^\circ C \leq T_A \leq +125^\circ C$		0.6		
Output Characteristics						
Output Voltage Swing from Rail		$R_L = 25k\Omega$		5	14	mV
		$-40^\circ C \leq T_A \leq +125^\circ C$			15.5	
		$R_L = 5k\Omega$		25	40	
		$-40^\circ C \leq T_A \leq +125^\circ C$			46	
Output Short-Circuit Current	I_{SC}	$V_S = 5V$		20		mA
Power Supply						
Operating Voltage Range	V_S		1.8		5.5	V
Quiescent Current/Amplifier	I_Q	$V_S = 5.5V, I_{OUT} = 0mA$		2.5	4.2	μA
		$-40^\circ C \leq T_A \leq +125^\circ C$			6.5	
Power Supply Rejection Ratio	PSRR	$V_S = 1.8V$ to $5.5V, V_{CM} = 0.6V$		2.5	12	$\mu V/V$
		$-40^\circ C \leq T_A \leq +125^\circ C$			14	
Dynamic Performance ($C_{LOAD} = 30pF$)						
Gain-Bandwidth Product	GBP			120		kHz
Slew Rate	SR	$G = +1$		0.08		V/ μs
Overload Recovery Time		$V_{IN} \times G > V_S$		25		μs
Turn-On Time	t_{ON}			0.2		ms
Noise						
Input Voltage Noise		$f = 0.1Hz$ to $10Hz$		3.5		μV_{P-P}
Input Voltage Noise Density	e_n	$f = 1kHz$		75		nV/\sqrt{Hz}
Input Current Noise Density	i_n	$f = 1kHz$		0.2		pA/\sqrt{Hz}

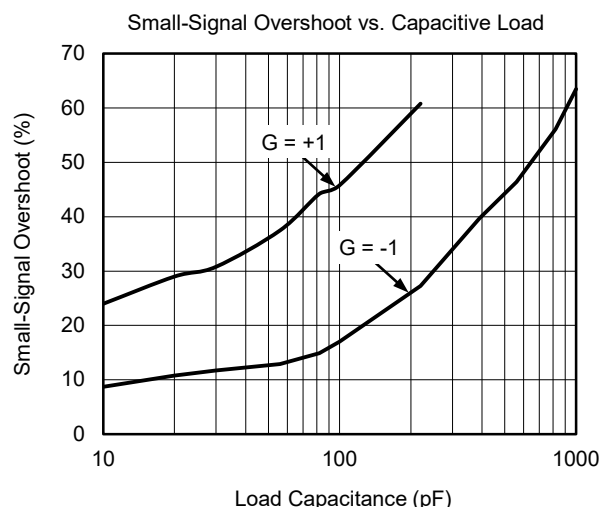
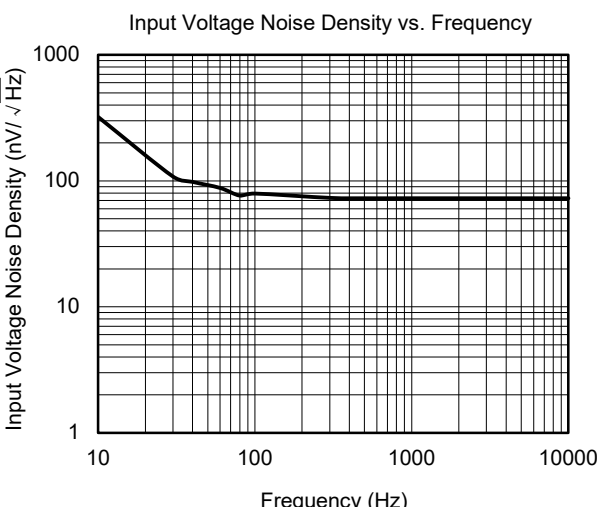
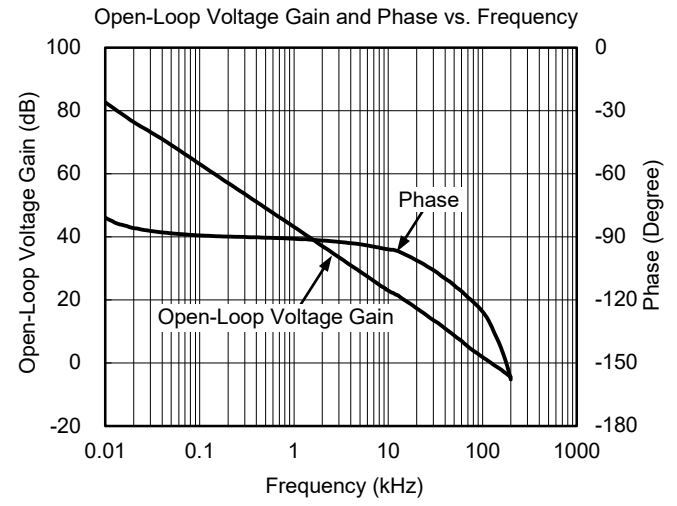
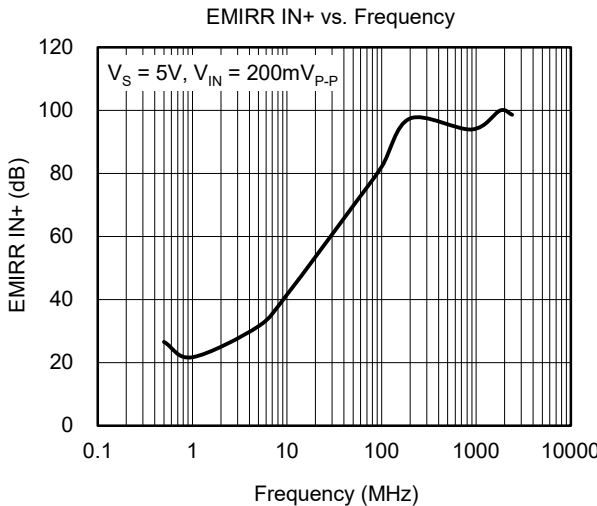
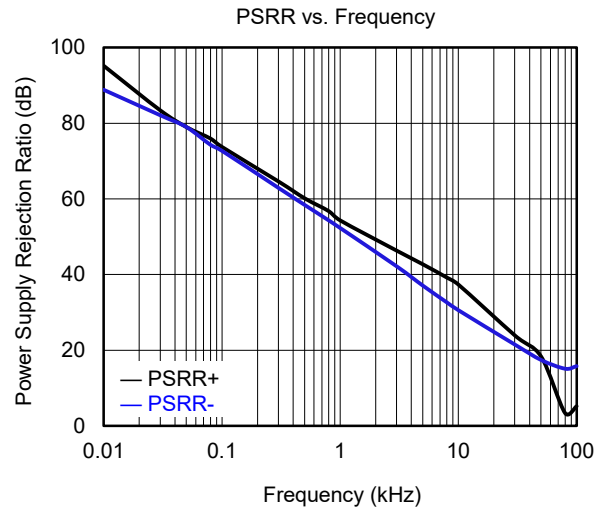
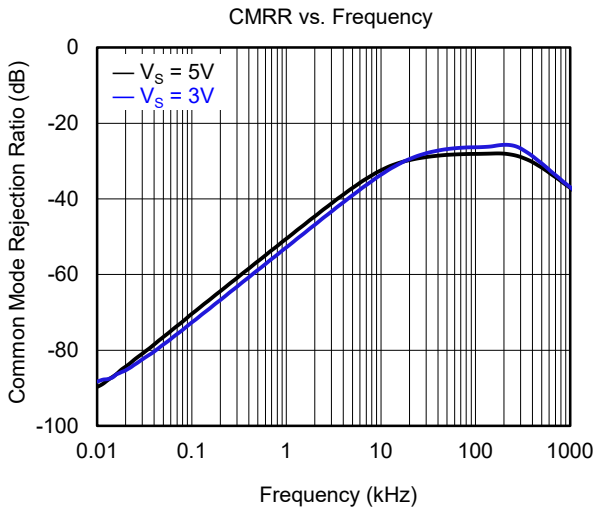
TYPICAL PERFORMANCE CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$ and $R_L = 25\text{k}\Omega$ connected to $V_S/2$, unless otherwise noted.



TYPICAL PERFORMANCE CHARACTERISTICS (continued)

At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$ and $R_L = 25\text{k}\Omega$ connected to $V_S/2$, unless otherwise noted.



TYPICAL PERFORMANCE CHARACTERISTICS (continued)

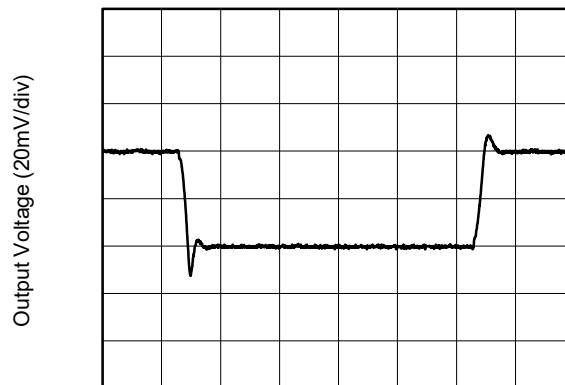
At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$ and $R_L = 25\text{k}\Omega$ connected to $V_S/2$, unless otherwise noted.

Large-Signal Step Response



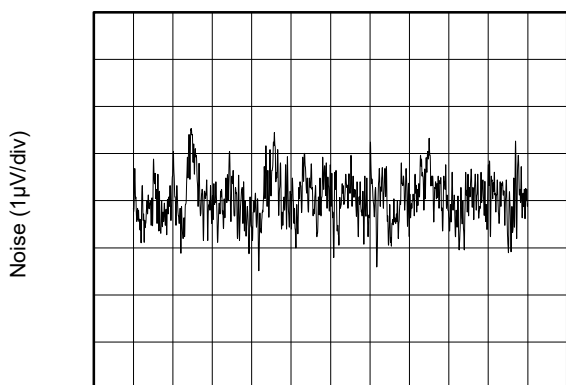
Time (50µs/div)

Small-Signal Step Response



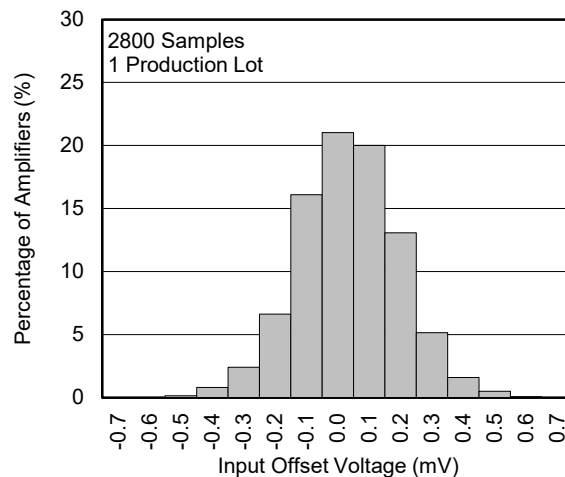
Time (25µs/div)

0.1Hz to 10Hz Noise

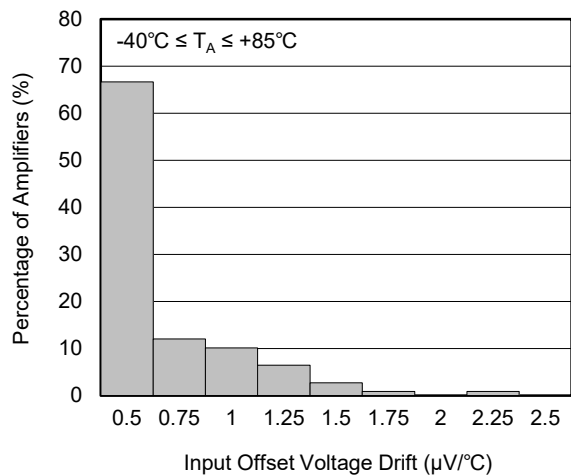


Time (2.5s/div)

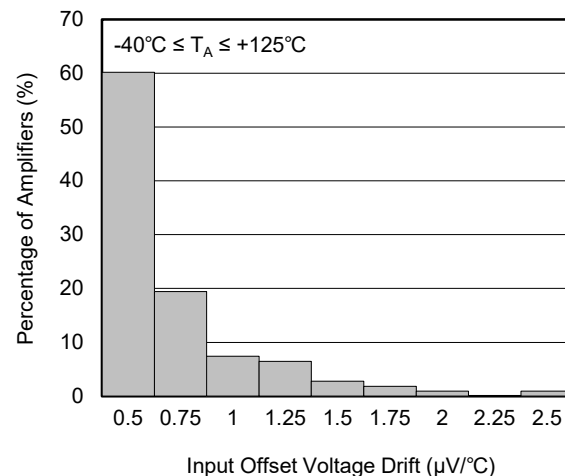
Input Offset Voltage Production Distribution



Input Offset Voltage Drift Distribution

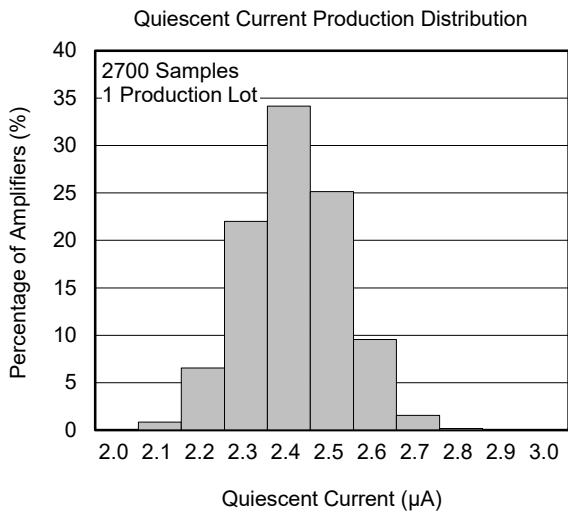


Input Offset Voltage Drift Distribution



TYPICAL PERFORMANCE CHARACTERISTICS (continued)

At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$ and $R_L = 25\text{k}\Omega$ connected to $V_S/2$, unless otherwise noted.



APPLICATION INFORMATION

The performance of the signal bandwidth and the noise is not decreased though the power consumption is minimized. In addition, the common mode rejection ratio (CMRR), power supply rejection ratio (PSRR) and the open loop gain (A_{OL}) are greater than 100dB typically.

The system components should be selected carefully if users are desired to minimize the power consumption, which means that the large resistance should be taken into account. However, there are stray capacitances in any PCB board, which means that the large capacitance should be combined with these capacitors (RC delay) to affect the signal bandwidth and the stability of the feedback system. To avoid this issue, a feedback capacitor is required to enhance the stability and limit any gain peaking or overshoot.

Also, for decoupling, a 0.1µF capacitor is required to be placed as close as possible to the power supply pin.

Operating Voltage

SGM8049-1/2/4 are typically tested or specified in the power supply range from 1.8V to 5.5V (or ±0.9V to ±2.75V).

Input Common Mode Voltage Range

For the common mode voltage at the inputs of SGM8049-1/2/4, it is operated from $(-V_S) - 0.1V$ to $(+V_S) + 0.1V$. The complementary structure at the input is applied for achieving the wide input common mode voltage range. The defined CMRR range is from $(-V_S)$ to $(+V_S) - 1.2V$. Between $(-V_S) - 0.1V$ and $(+V_S) + 0.1V$, the offset voltage of the device in this region is higher since this is the transition region for the input structure of the SGM8049-1/2/4.

Input Over-Voltage Protection

The typical input biasing current is 1pA. However, if the input voltage level is 0.5V greater than the power supply rails of the operational amplifier, the current will be increased exponentially. Also, to keep the input voltage within the maximum allowed region, a resistor

should be placed at the input of the amplifier to limit the input current within 10mA, which is shown in Figure 2.

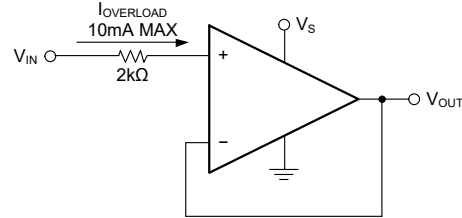


Figure 2. Protection for Input Current when Supply Voltage is Exceeded

Noise Performance

The performance of noise for SGM8049-1/2/4 is excellent. The resistors should be selected accordingly to prevent the thermal noise from being the dominant one, as the 0.1Hz to 10Hz noise for SGM8049-1/2/4 is just 3.5µV_{P-P}, and wideband noise is 75nV/√Hz.

Driving Capacitive Load with Stability

For unity-gain buffer application, the overshoot or gain peaking would be made if the load capacitance is greater than 30pF. To improve the ability of capacitive loading, one way is improving the voltage gain, and the other way is adding 10Ω to 20Ω isolated resistor at the output stage, which is shown in Figure 3. With this resistor, the ringing and gain peaking can be eliminated for light capacitive loading. However, if a resistive load is connected in parallel with the C_L , the output will be divided by the R_S and R_L . Generally, if the R_L is large, the influence is negligible.

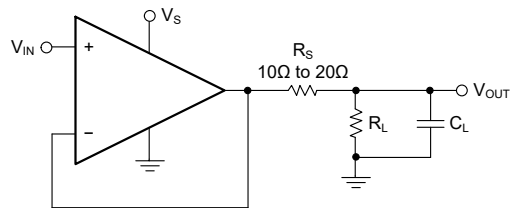


Figure 3. Capacitive Load Drive Improved by Series Resistor in Unity-Gain Buffer Configuration

APPLICATION INFORMATION (continued)

For the inverting unity-gain application, the phase margin of the loop gain can be decreased by reacting of the gain and feedback resistors and the parasitic capacitance which is at the negative input pin. For best performance, decreasing the R_F and R_{IN} should be taken into account. However, if users desire to use large feedback and gain resistors, placing a 4pF to 6pF capacitor in parallel with the R_F is a good choice for enhancing the stability of the feedback loop. Also, the gain peaking and the overshoot will be decreased accordingly. In Figure 4, C_{IN} indicates the parasitic capacitance for the operational amplifier and the PCB.

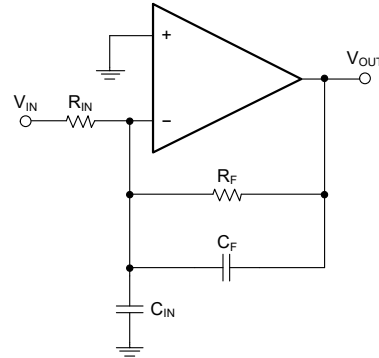


Figure 4. Enhancing the Stability of Large R_F and R_{IN}

Figure 5 through Figure 9 illustrate some low power application examples.

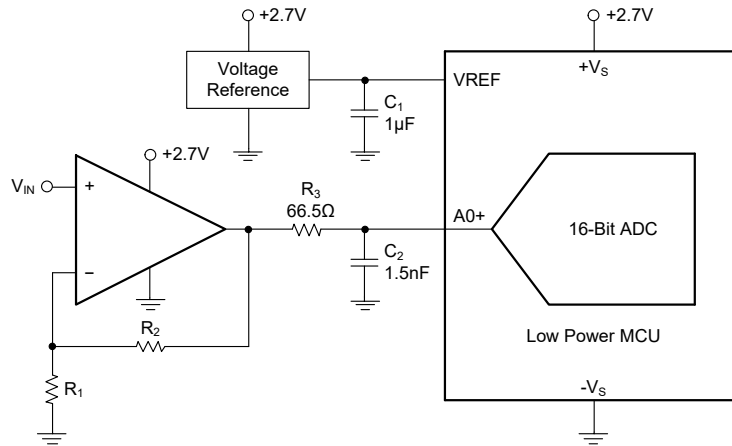


Figure 5. Single Amplifier Configurations for Driving Unipolar Precision ADC

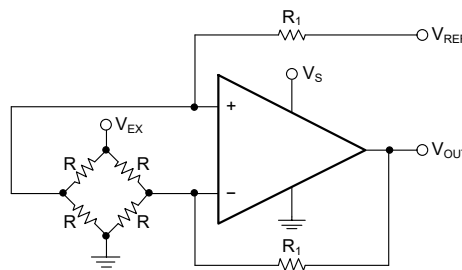
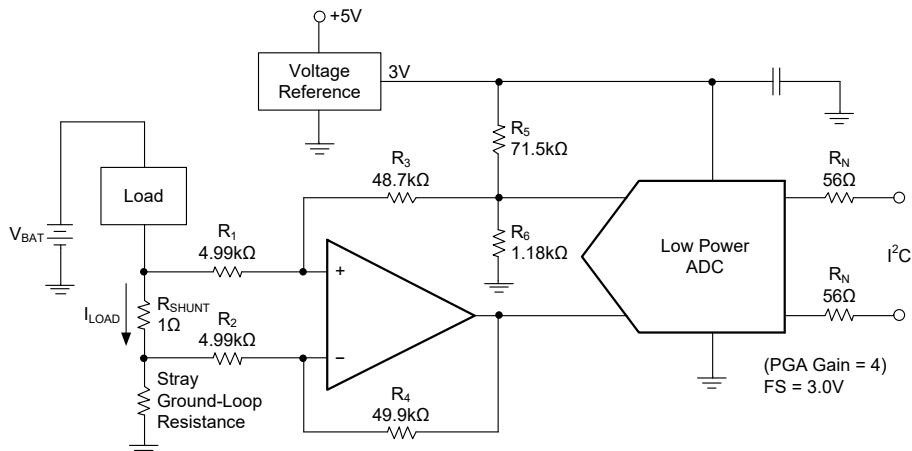


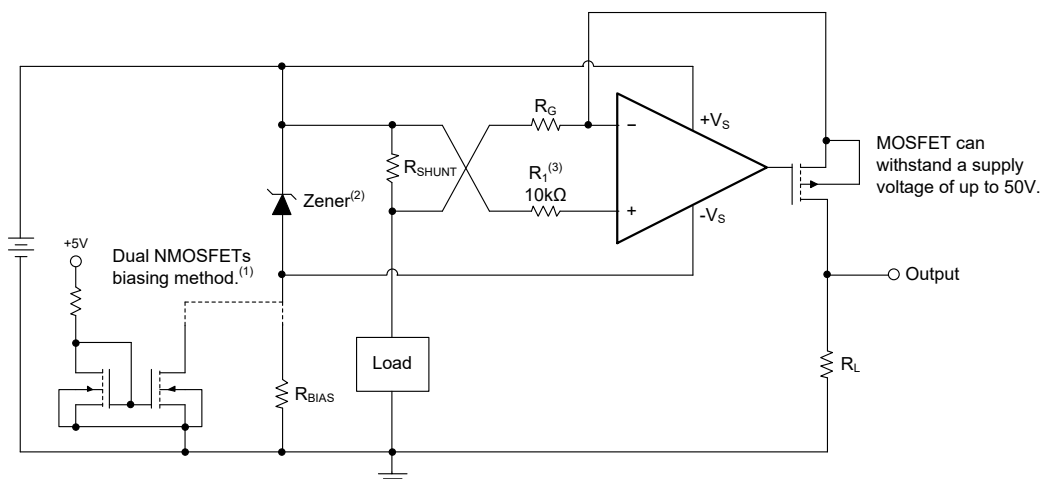
Figure 6. Bridge Amplifier Using a Single Operational Amplifier

APPLICATION INFORMATION (continued)



NOTE: 1% resistors can provide sufficient common mode rejection to reduce the adverse effects caused by small ground-loop errors.

Figure 7. Low-side Current Shunt Monitor



NOTES:

1. Use Zener biasing resistor or dual NMOSFETs to provide the required biasing voltage.
2. The rated value of the Zener diode is the power supply capability of the operational amplifier, which is 5.6V for SGM8049-1/2/4.
3. Current-limit resistor.

Figure 8. High-side Current Measurement

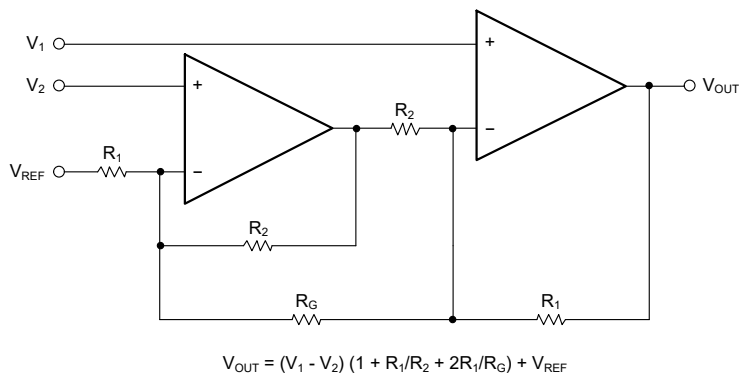


Figure 9. Low Power Instrumentation Amplifier Consisting of Two Operational Amplifiers

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

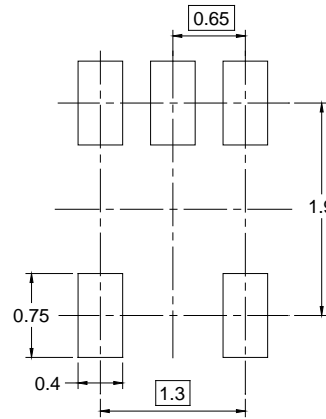
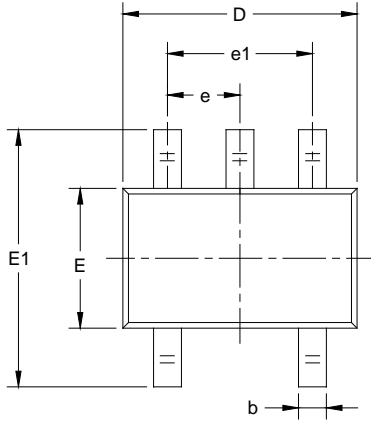
AUGUST 2023 – REV.A.1 to REV.A.2	Page
Updated Typical Performance Characteristics section	7
Updated Package Outline Dimensions section	14

AUGUST 2017 – REV.A to REV.A.1	Page
Updated Typical Performance Characteristics section	8

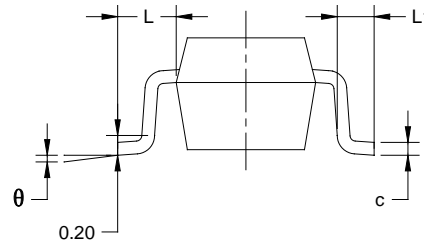
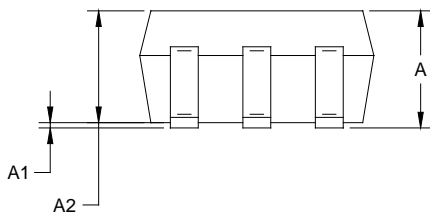
Changes from Original (NOVEMBER 2015) to REV.A	Page
Changed from product preview to production data.....	All

PACKAGE OUTLINE DIMENSIONS

SC70-5



RECOMMENDED LAND PATTERN (Unit: mm)



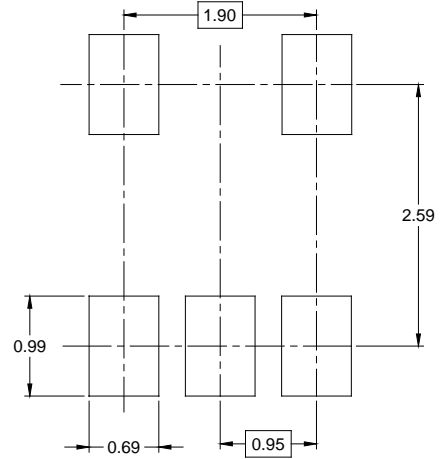
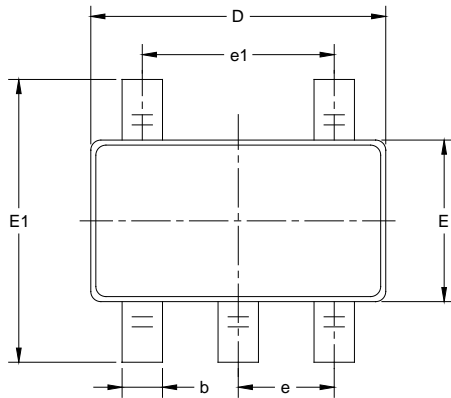
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.800	1.100	0.031	0.043
A1	0.000	0.100	0.000	0.004
A2	0.800	1.000	0.031	0.039
b	0.150	0.350	0.006	0.014
c	0.080	0.220	0.003	0.009
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.65 TYP		0.026 TYP	
e1	1.300 BSC		0.051 BSC	
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

NOTES:

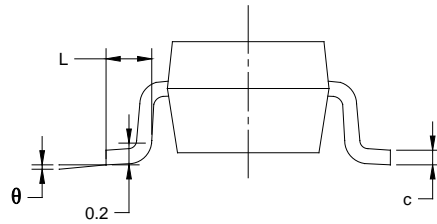
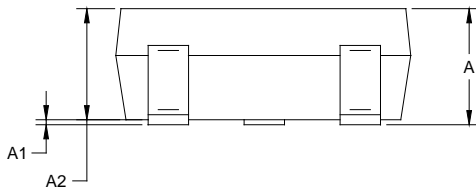
1. Body dimensions do not include mold flash or protrusion.
2. This drawing is subject to change without notice.

PACKAGE OUTLINE DIMENSIONS

SOT-23-5



RECOMMENDED LAND PATTERN (Unit: mm)



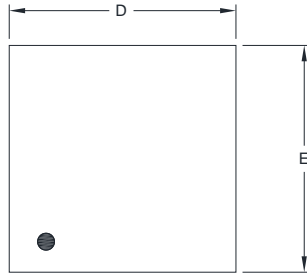
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 BSC		0.037 BSC	
e1	1.900 BSC		0.075 BSC	
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

NOTES:

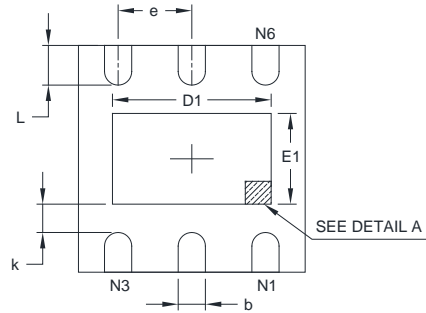
1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.

PACKAGE OUTLINE DIMENSIONS

TDFN-2x2-6L



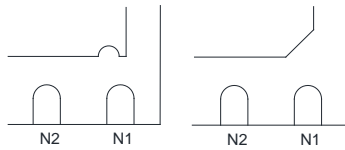
TOP VIEW



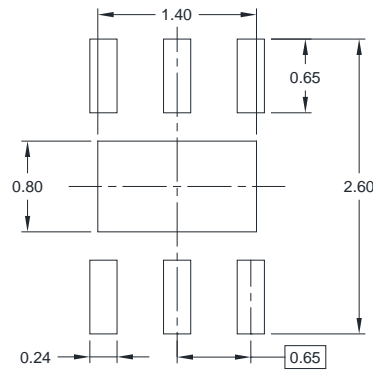
BOTTOM VIEW



SIDE VIEW



DETAIL A



RECOMMENDED LAND PATTERN (Unit: mm)

Pin #1 ID and Tie Bar Mark Options

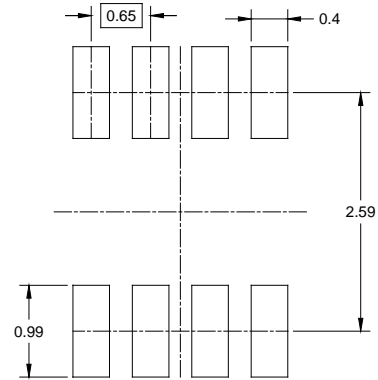
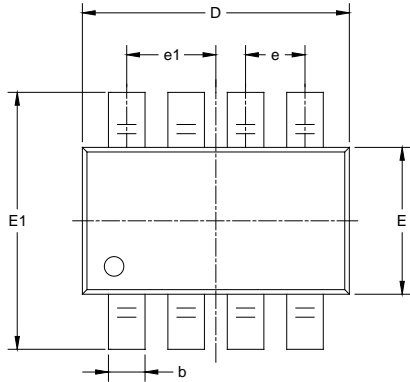
NOTE: The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203 REF		0.008 REF	
D	1.900	2.100	0.075	0.083
D1	1.100	1.450	0.043	0.057
E	1.900	2.100	0.075	0.083
E1	0.600	0.850	0.024	0.034
k	0.200 MIN		0.008 MIN	
b	0.180	0.300	0.007	0.012
e	0.650 TYP		0.026 TYP	
L	0.250	0.450	0.010	0.018

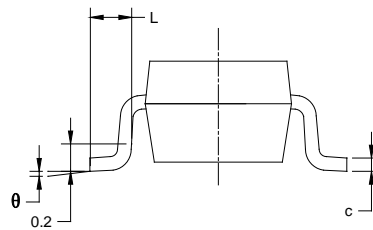
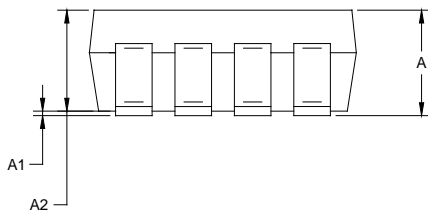
NOTE: This drawing is subject to change without notice.

PACKAGE OUTLINE DIMENSIONS

SOT-23-8



RECOMMENDED LAND PATTERN (Unit: mm)



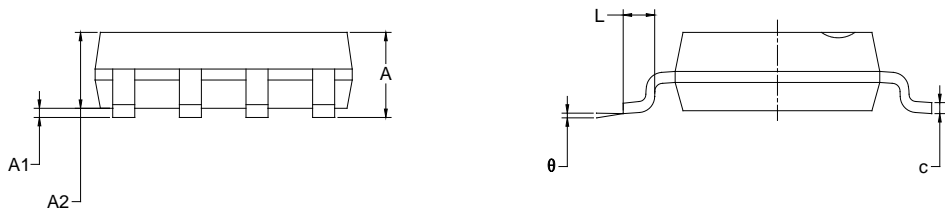
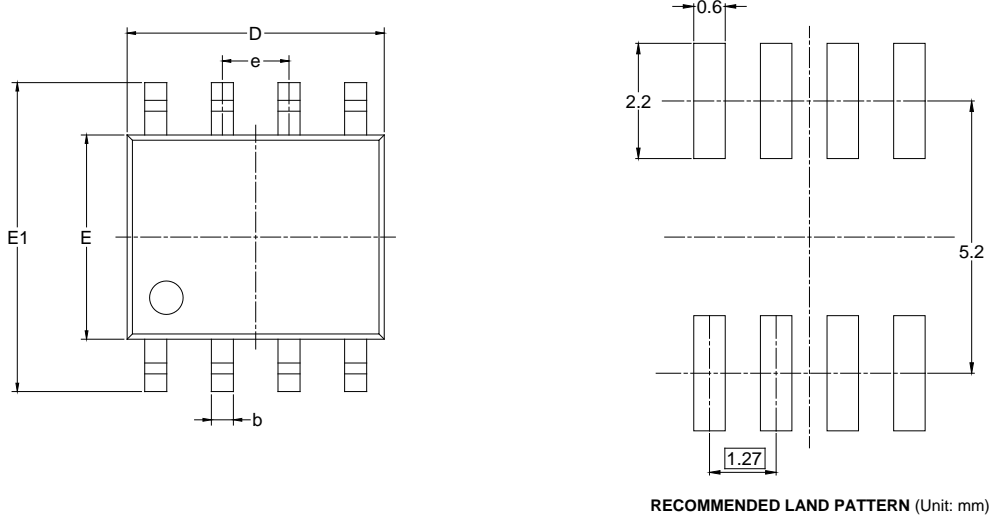
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.650 BSC		0.026 BSC	
e1	0.975 BSC		0.038 BSC	
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

NOTES:

1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.

PACKAGE OUTLINE DIMENSIONS

SOIC-8

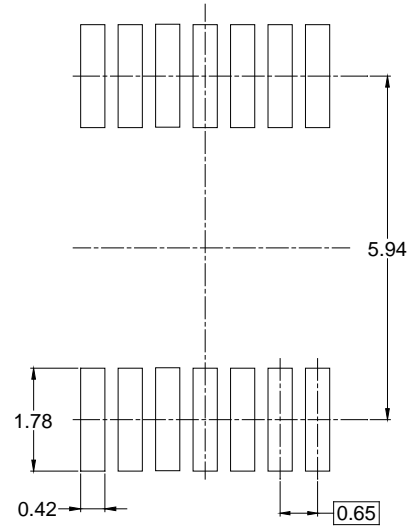
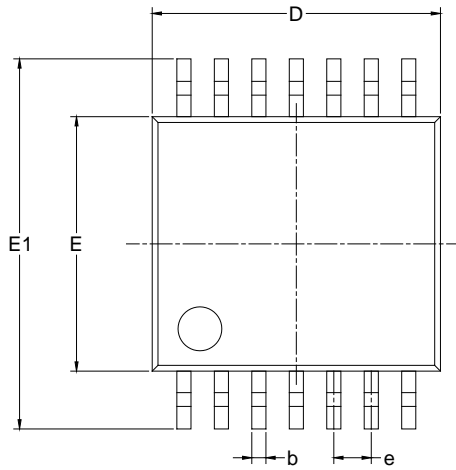


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.27 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

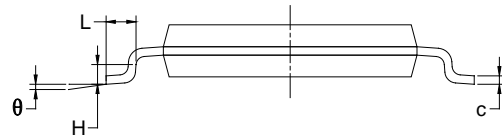
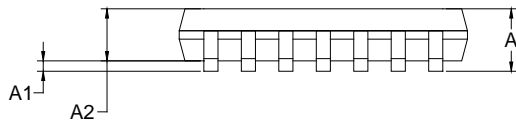
NOTES:
 1. Body dimensions do not include mode flash or protrusion.
 2. This drawing is subject to change without notice.

PACKAGE OUTLINE DIMENSIONS

TSSOP-14



RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A		1.200		0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D	4.860	5.100	0.191	0.201
E	4.300	4.500	0.169	0.177
E1	6.250	6.550	0.246	0.258
e	0.650 BSC		0.026 BSC	
L	0.500	0.700	0.02	0.028
H	0.25 TYP		0.01 TYP	
θ	1°	7°	1°	7°

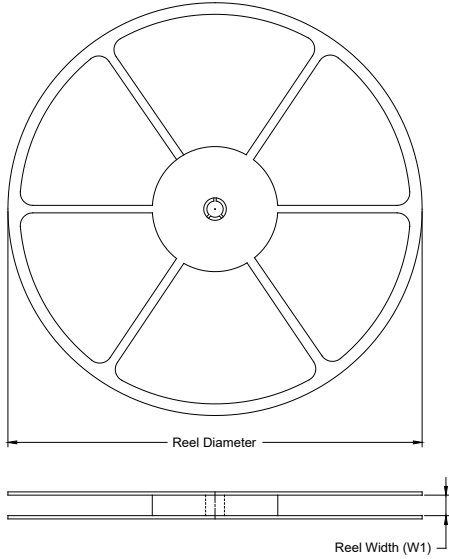
NOTES:

1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.

PACKAGE INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SC70-5	7"	9.5	2.40	2.50	1.20	4.0	4.0	2.0	8.0	Q3
SOT-23-5	7"	9.5	3.20	3.20	1.40	4.0	4.0	2.0	8.0	Q3
TDFN-2×2-6L	7"	9.5	2.30	2.30	1.10	4.0	4.0	2.0	8.0	Q1
SOT-23-8	7"	9.5	3.23	3.17	1.37	4.0	4.0	2.0	8.0	Q3
SOIC-8	13"	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1
TSSOP-14	13"	12.4	6.40	5.40	1.50	4.0	8.0	2.0	12.0	Q1

D30001

PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18
13"	386	280	370	5

DD0002